

## AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

3. (Currently Amended) The method of claim ~~11~~19 30, wherein said sinterable particulate material or materials are selected from the class of metals, ceramics and mixtures of metals and ceramics.

5. (Currently Amended) The method of claim ~~11~~19 30, wherein said degradable organic thermoplastic material or materials are selected from the class of polyolefins, waxes, plasticizers, greases, oils, surfactants and mixtures of these.

6. (Currently Amended) The method of claim ~~11~~19 30, wherein ~~the~~ said tools include semiconductor wire bonding capillaries or blanks for semiconductor wire bonding capillaries.

11. (Currently Amended) The method of claim ~~11~~19 30, wherein ~~the~~ said tools include semiconductor wire bonding wedges or blanks for ~~the~~ semiconductor wire bonding wedges.

19. (Cancelled)

20. (Cancelled)

21. (Cancelled)

22. (Cancelled)

23. (Cancelled)

24. (Cancelled)

25. (Cancelled)

26. (Cancelled)

27. (Cancelled)

28. (Cancelled)

29. (Cancelled)

30. (New) A method for producing tools or blanks for tools of reduced dimensions for use in the assembly and interconnection of semiconductor chips, comprising:

- a. providing at least one sinterable material in fine particulate form and at least one degradable organic thermoplastic material,
- b. accurately determining the volumes of said sinterable particulate material or materials and the volumes of said thermoplastic material or materials needed to yield the desired shrinkage upon sintering in said tools or blanks for tools of reduced dimensions,
- c. mixing together said accurately determined volumes of said sinterable particulate material or materials with said thermoplastic material or materials to form a thermoplastic compound,
- d. forming said thermoplastic compound into green semiconductor wire bonding tools or semiconductor wire bonding tool blanks,

e. extracting substantially all of the organic thermoplastic material from said green tools or blanks and sintering the thus obtained organic-free preforms into dense end products.

31. (New) The method of claim 30 wherein the dimensions of said tools or blanks for tools of reduced dimensions can be further reduced by increasing the ratio of the volume of said thermoplastic material or materials to the volume of said sinterable particulate material or materials in said thermoplastic compound.